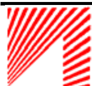
Material Declaration

Package Type	QFN-20 Pin
Package Size	9 X 9
Terminal Finish	Tin Plate
Weight (mg)	220
MSL	3

Series	CCBC3150

Homogenous Material	Element	Content (mg)	Content (wt%)	CAS #
Mold Compound	Fused silica	154	95	60676-86-0
	Epoxy + Phenol Resin		5	Trade Secret
	Carbon black		0.5	1333-86-4
Lead Frame	Cu	45	97	7440-31-5
	Fe		2	7439-89-6
	Zn		0.2	7440-66-6
	Ag		1	7440-57-5
Die Attach	Ag	1	75	7440-57-5
	Epoxy resins		20	Trade Secret
	Aromatic polyamine		5	Trade Secret
Die Coat	Dimethyl Siloxane w/ Methyl Silsesquioxane Trimethylsiloxy-term and Dimetylvinysiloxy-term	1	100	PMN910613
EnerChip Die	Si	16	93	7440-21-3
	LiPON		3.1	No Number Assigned
	LiCoO2		3.1	12190-79-3
	Al		<.1%	7429-90-5
	Ni		<.1%	7439-89-6
	Ti		<.1%	7440-32-6
	Polyimide		<.1%	Trade Secret
CBC910 ASIC Device	Si	1.5	100	7440-21-3
Bond Wire	Au	1.5	99	7440-57-5
Total		220		

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products.



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